

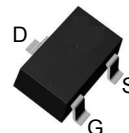


**P-Channl Enhancement Mode MOSFET**

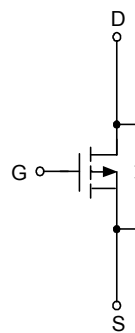
**Features**

- 20V/-4.6A ,  
 $R_{DS(ON)} = 38m\Omega$  (typ.) @  $V_{GS} = -4.5V$   
 $R_{DS(ON)} = 52m\Omega$  (typ.) @  $V_{GS} = -2.5V$   
 $R_{DS(ON)} = 76m\Omega$  (typ.) @  $V_{GS} = -1.8V$
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

**Pin Description**



Top View of SOT-23



P-Channel MOSFET

**Applications**

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

**Absolute Maximum Ratings** ( $T_A = 25^\circ C$  unless otherwise noted)

Symbol	Parameter	Rating	Unit	
$V_{DSS}$	Drain-Source Voltage	-20	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 12$		
$I_D^*$	Continuous Drain Current	$T_A = 25^\circ C$	-4.6	A
		$T_A = 70^\circ C$	-3.7	
$I_{DM}^*$	300 $\mu$ s Pulsed Drain Current	$T_A = 25^\circ C$	-18.6	
		$T_A = 70^\circ C$	-14.9	
$I_S^*$	Diode Continuous Forward Current	-1		
$T_J$	Maximum Junction Temperature	150	$^\circ C$	
$T_{STG}$	Storage Temperature Range	-55 to 150		
$P_D^*$	Maximum Power Dissipation	$T_A = 25^\circ C$	1.56	W
		$T_A = 70^\circ C$	1.0	
$R_{\theta JA}^*$	Thermal Resistance-Junction to Ambient	$t \leq 10s$	80	$^\circ C/W$
		Steady state	120	
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	Steady state	52	

Note : \*Surface Mounted on 1in<sup>2</sup> pad area, t  $\leq$  10sec.



**P-Channl Enhancement Mode MOSFET**

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=-250\mu A$	-20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-16V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	-1	$\mu A$
			-	-	-30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-0.5	-0.7	-1	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^a$	Drain-Source On-State Resistance	$V_{GS}=-4.5V, I_{DS}=-4.6A$	-	38	48	m $\Omega$
		$V_{GS}=-2.5V, I_{DS}=-2.9A$	-	52	70	
		$V_{GS}=-1.8V, I_{DS}=-1.5A$	-	76	110	
$V_{SD}^a$	Diode Forward Voltage	$I_{SD}=-1A, V_{GS}=0V$	-	-0.7	-1	V
<b>Gate Charge Characteristics<sup>b</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=-10V, V_{GS}=-4.5V,$ $I_{DS}=-4.6A$	-	6.8	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.8	-	
$Q_{gd}$	Gate-Drain Charge		-	2.5	-	
<b>Dynamic Characteristics<sup>b</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	3.6	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-10V,$ Frequency=1.0MHz	-	590	-	pF
$C_{oss}$	Output Capacitance		-	122	-	
$C_{rss}$	Reverse Transfer Capacitance		-	92	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-10V, R_L=10\Omega,$ $I_{DS}=-1A, V_{GEN}=-4.5V,$ $R_G=6\Omega$	-	7.2	-	ns
$t_r$	Turn-on Rise Time		-	13.4	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	26	-	
$t_f$	Turn-off Fall Time		-	17	-	
$t_{rr}$	Reverse Recovery Time	$I_{SD}=-4.6A, dI_{SD}/dt = 100A/\mu s$	-	18	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	7	-	nC

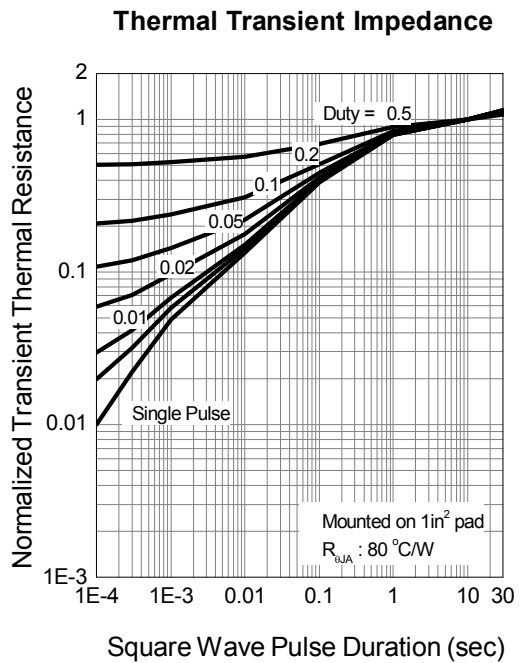
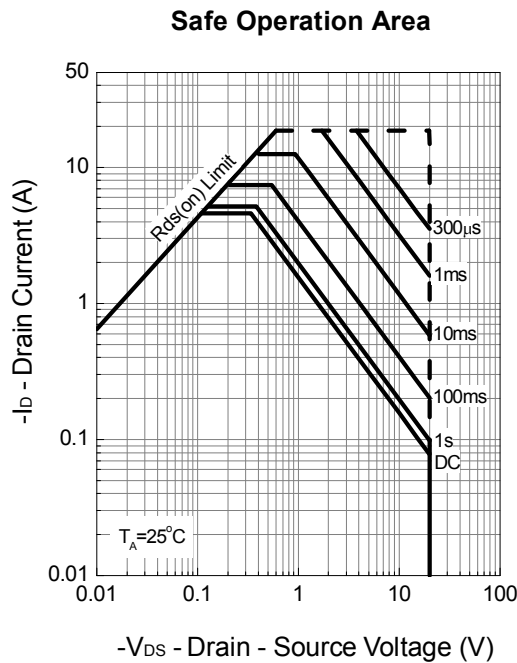
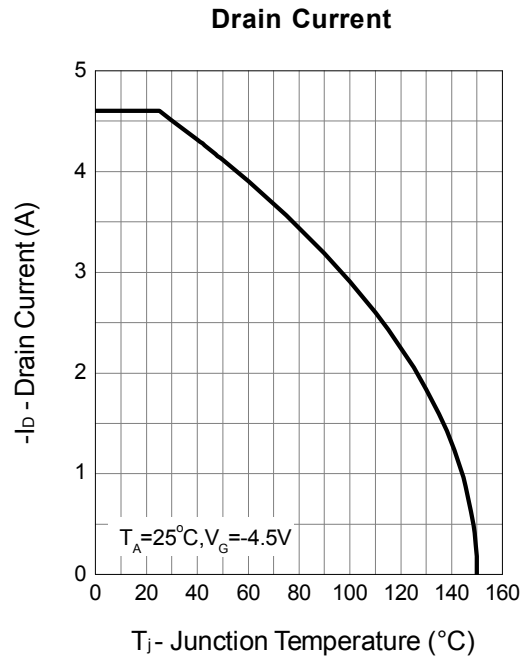
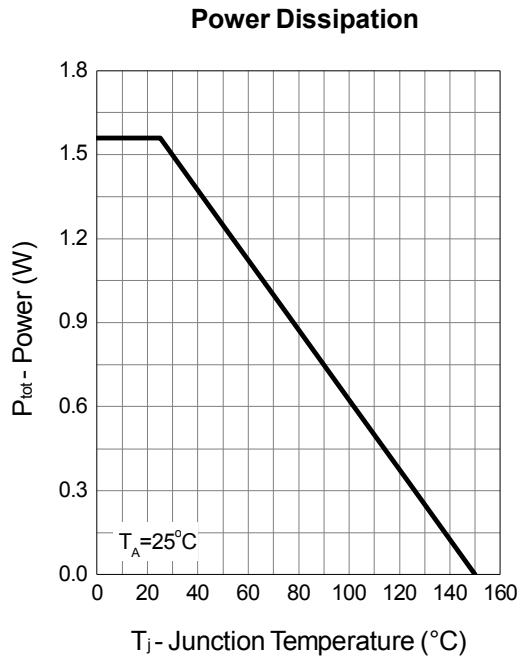
Note a : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

Note b : Guaranteed by design, not subject to production testing.



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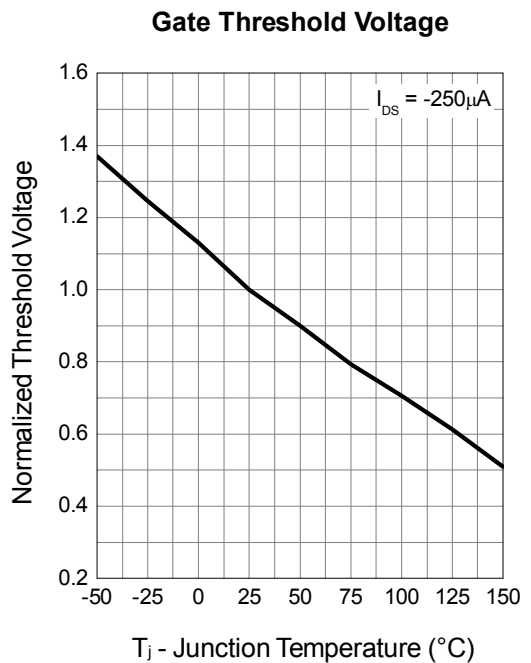
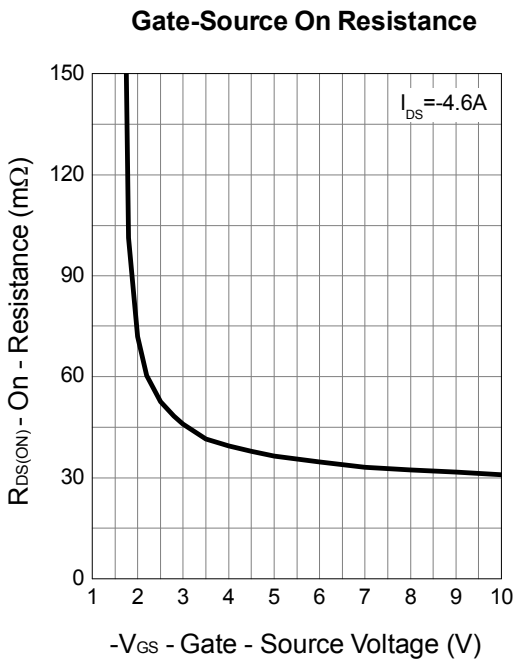
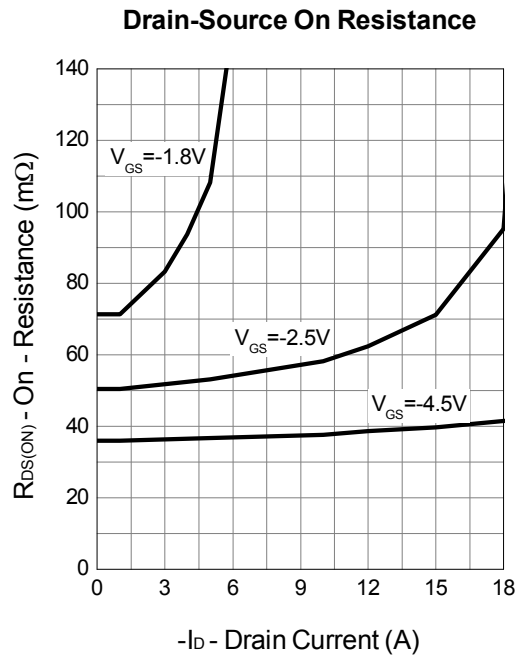
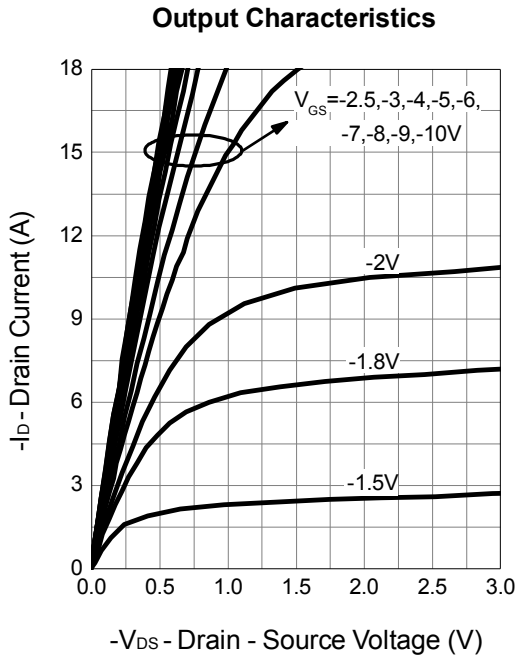
Typical Operating Characteristics





P-Channl Enhancement Mode MOSFET

Typical Operating Characteristics (Cont.)

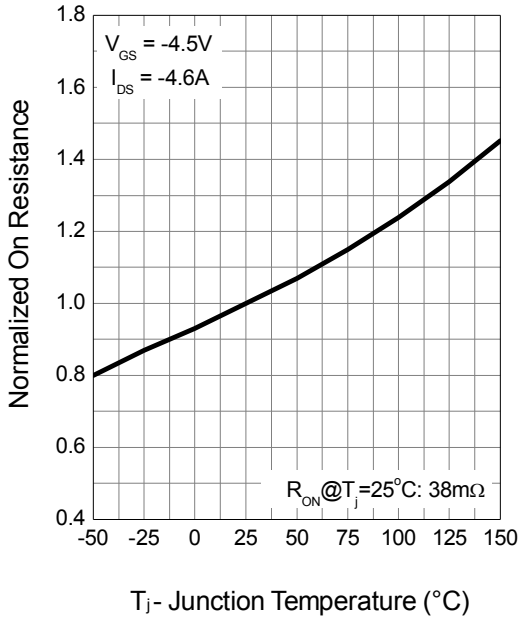




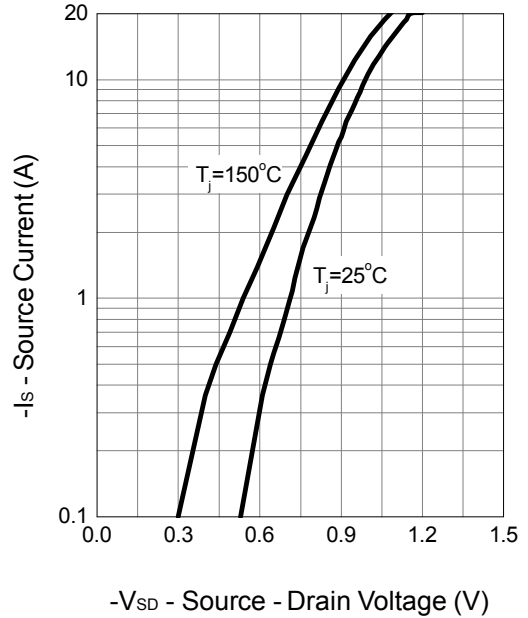
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Typical Operating Characteristics (Cont.)

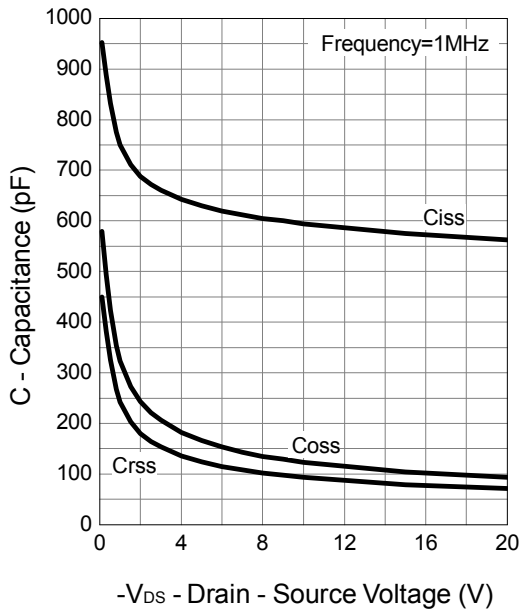
Drain-Source On Resistance



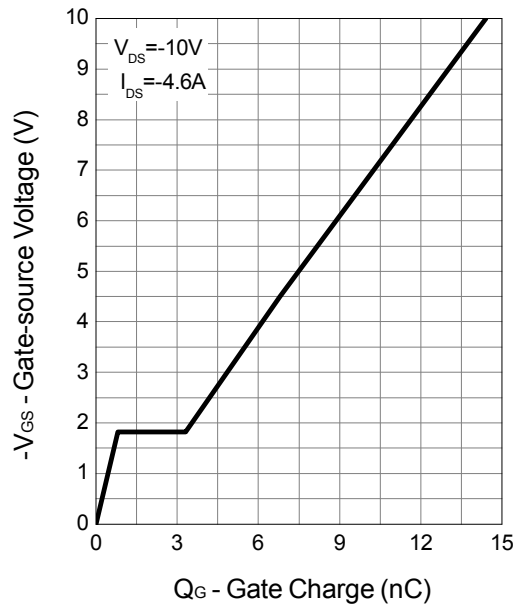
Source-Drain Diode Forward



Capacitance



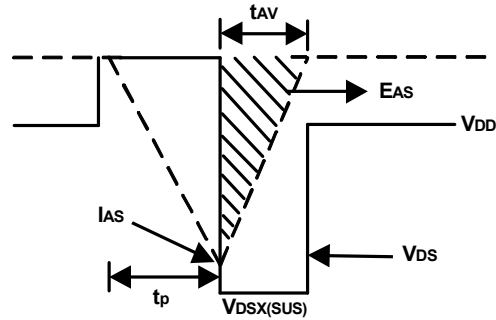
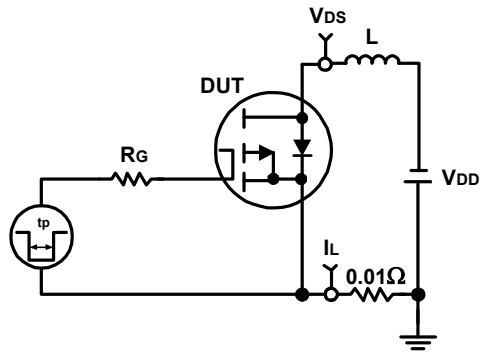
Gate Charge



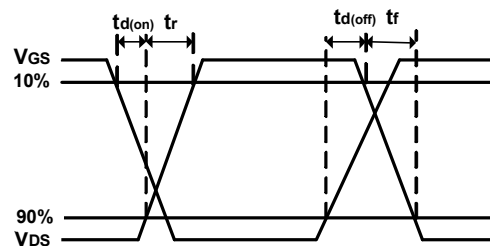
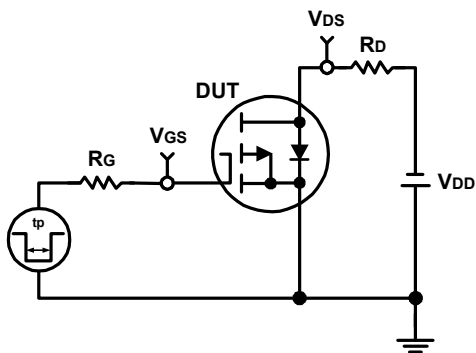


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Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms

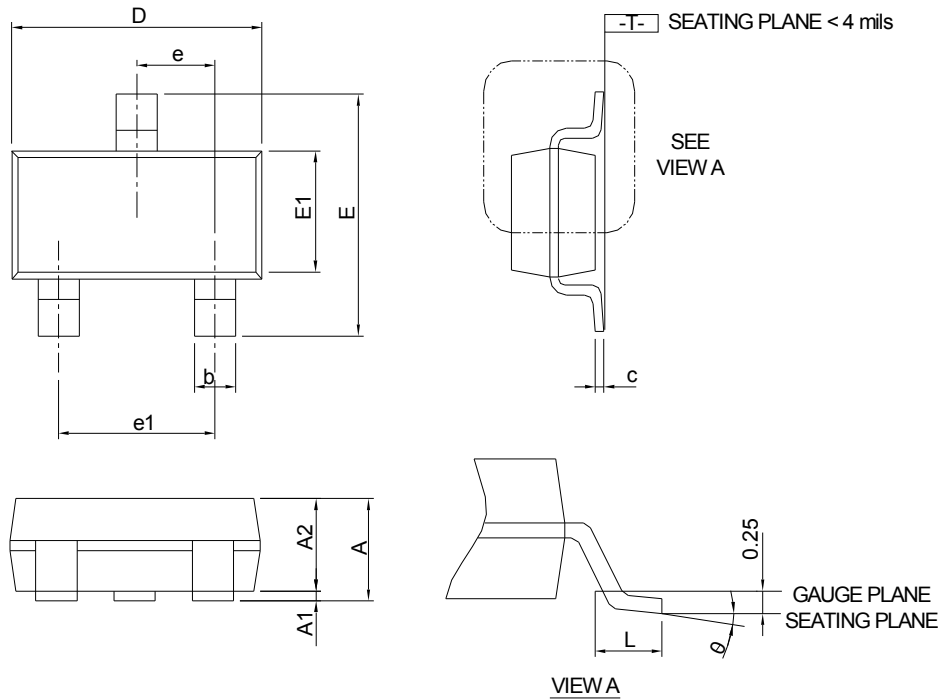




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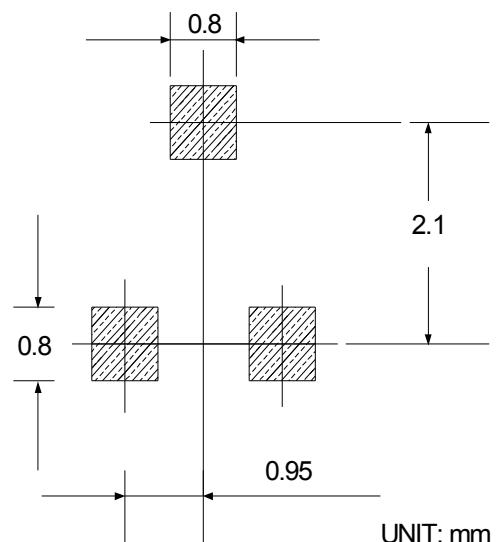
Package Information

SOT-23



SYMBOLS	SOT-23-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.20	-	0.047
A1	0.00	0.08	0.000	0.003
A2	0.90	1.12	0.035	0.044
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.70	3.10	0.106	0.122
E	2.25	2.55	0.102	0.118
E1	1.20	1.40	0.055	0.071
e	0.95 BSC		0.037 BSC	
e1	1.90 BSC		0.075 BSC	
L	0.30	0.60	0.012	0.024
$\theta$	0° - 8°		0° - 8°	

RECOMMENDED LAND PATTERN



Note : Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.